



Supermicro's Capabilities can help your partner be successful.

Your partner's success is your success.

13th Generation Solutions Channel Success

Versatile, Fast, and Efficient Building Block Systems
Optimized for Advanced Data Center Workloads

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Why Supermicro?



GREEN Computing

Innovation

Quality

Customization

Product Fit

Collaboration

Availability



Total Solution Rack Integration

Broad and Deep Product Portfolio
Covering Leading **Market Segments**

Well-Thought SKU Structure
Global SKUs, Standard & OEM Solution
MB, Barebones and Systems

State-of-the-Art Product
Designed **in US**. Tested with Laser Focus on
Quality

First-to-Market
Seed & Early Access Program for New
Introductions

Customer Focus
ISV Partner Integrations
Quick **Turnaround** for Channel Support
Training, **Collateral**, Messaging and Promotion

Supermicro Services
For Complete/Tested Systems
For Channel's End Customers
24H Hot line and Global onsite and RMA services

MBD design is important



[Home](#) [CPU](#) [Monitor](#) [GPU](#) [RAM](#)

Stability

One of the common failure points of a cheap motherboard is the quality of components, especially the capacitors. The capacitors are devices that store electrical charge. They mostly fail if they are made of poor-quality materials. Besides capacitors and inductors, the PCB quality, registers, and VRM quality also matter.

The VRM quality can sometimes determine the CPU clock speeds. A poorly designed VRM can impact the CPU voltage, and the processor frequency can degenerate.

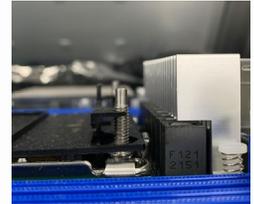
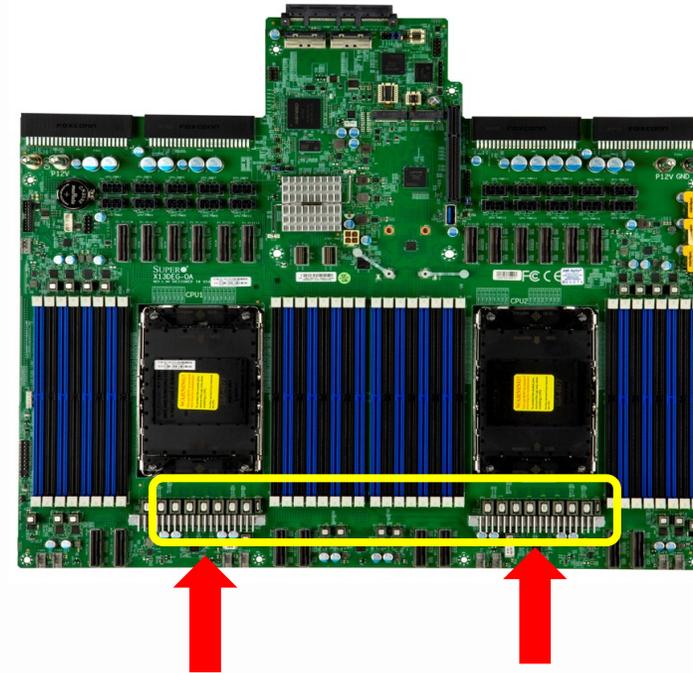
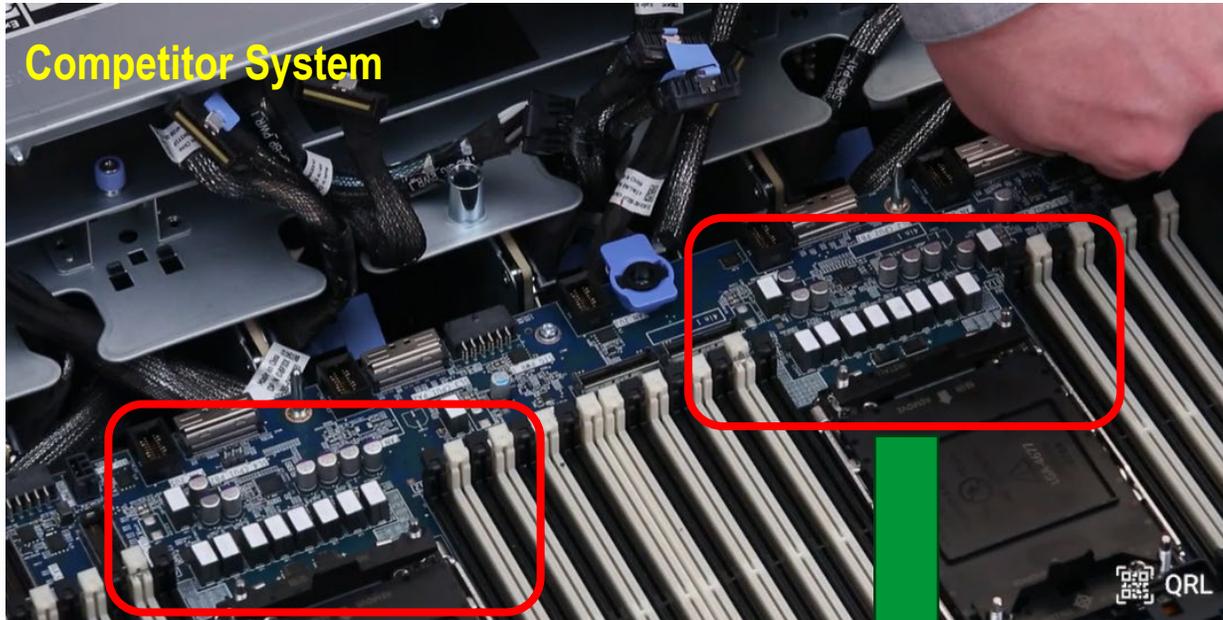
A decent motherboard is usually equipped with enhanced protection measures such as anti-surge, over-voltage, power, current protection measures, short circuit, over-temperature protections, etc.

A failure of the mainboard means your attached components are also at risk. If you are building your PC with high-quality components, you should also be careful with your motherboard choice.

Robust Product Design

- Stable System / Solution Operation
- Less product trouble shooting cases (Other component damage or etc.)
- Good user usage experience

Better Product Design



Extra heatsink to dispatch heat away

- When capacitor or circuit surface are over heated (Heavy workload)
 - Unstable operation
 - High system failure potential

- Provide stable system / solution operation
 - System Restart issue
 - System Freezes or Crashes
 - Entire system malfunctions

The Supermicro Advantage

Supermicro Total IT Solutions

- Our Gen 13 systems with have achieved over 50 world record performance awards
- Rack Scale plug-and-play service delivers complete, validated solutions in weeks, not months
- Production capacity of up to 3,500 racks per month worldwide
- Made in the USA program
- Industry standard compliance for attestation of components throughout the entire supply chain



Why SMC can help Channel/SI/VAR/Disti



1. Market need high computation high density system deployment

- Gen5 devices validation
- System is more complex for production
- Flexible infrastructure

2. Performance

3. Security

4. Fast turn around deployment

5. One stop shop “Tech Depot”

6. Best TCO

Market Segments:



Enterprise Server



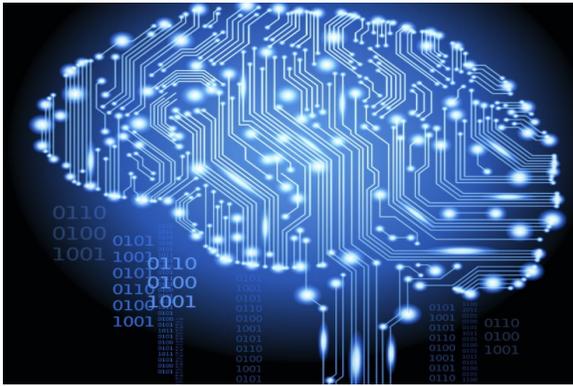
Cloud Computing



Big Data Analytics



Hyper converged Storage



AI Inference and Machine Learning



Virtualization



5G Core and Edge

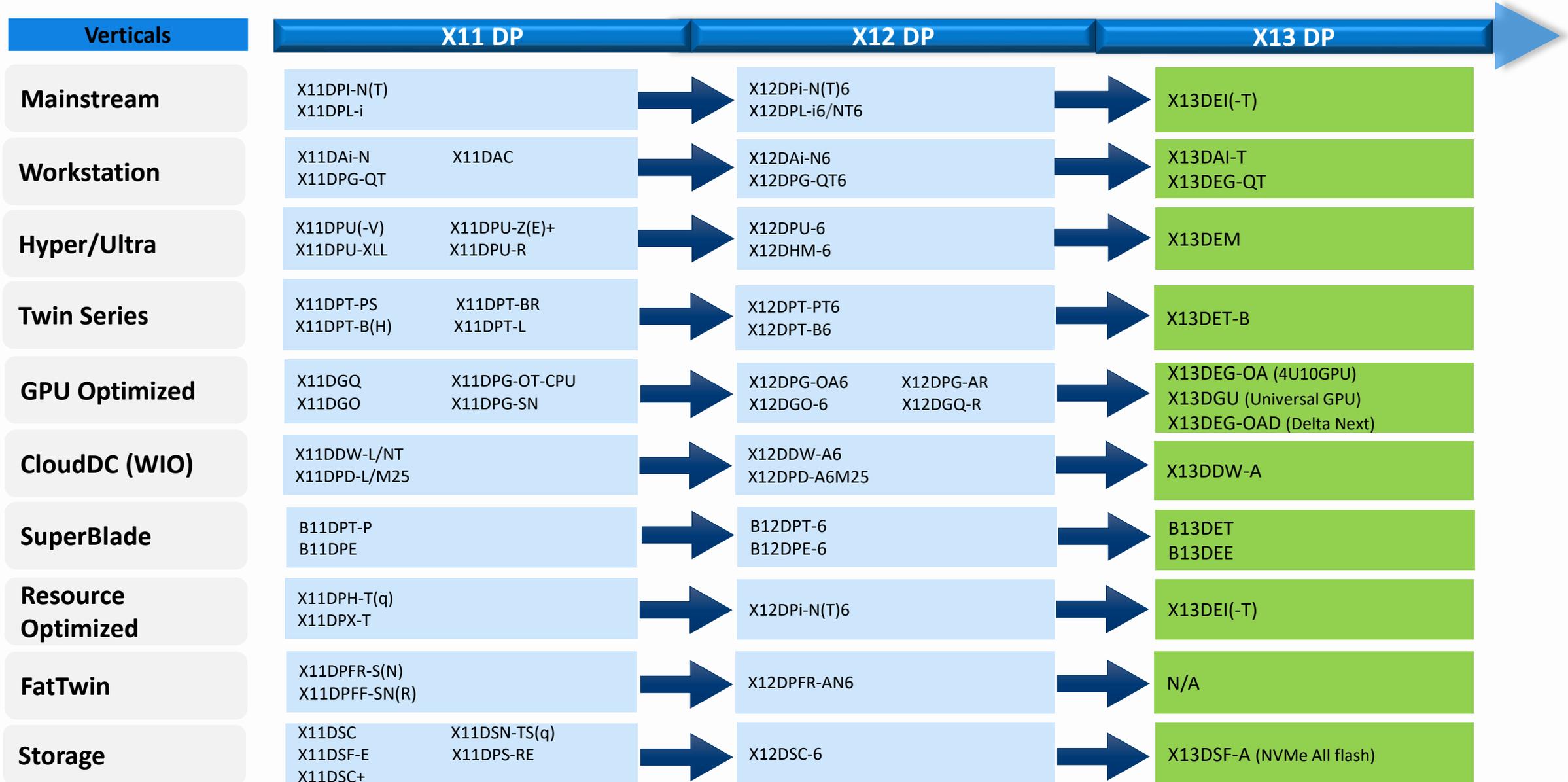


Telco Micro Data Center

X13 / Sapphire Rapids (SPR) Key Features

- Increased, Scalable performance
 - **50%** increased CPU cores (40 cores → 60 cores).
 - Up to **4UPI** per CPU @ higher speed 16GT/s.
 - TDP up to 350W, off road map CPU support.
- Breakthrough Memory & I/O
 - **1.5x** faster memory speed (DDR4 @3200 → **DDR5 @4800 MT/s**).
 - More PCIe lanes (PCIe 4.0 64 Lanes → **PCIe 5.0 80 Lanes**).
 - HBM (High Bandwidth Memory), for selected SKUs.
 - **CXL (Compute Express Link)**.
 - AMX (Advanced Matrix Extensions)
- Enhanced Security
 - SMC RoT 2.0 (immutable security, faster tier of eMMC storage)

Intel Dual Socket MBD Transition Chart



X13DEI-T-Mainstream

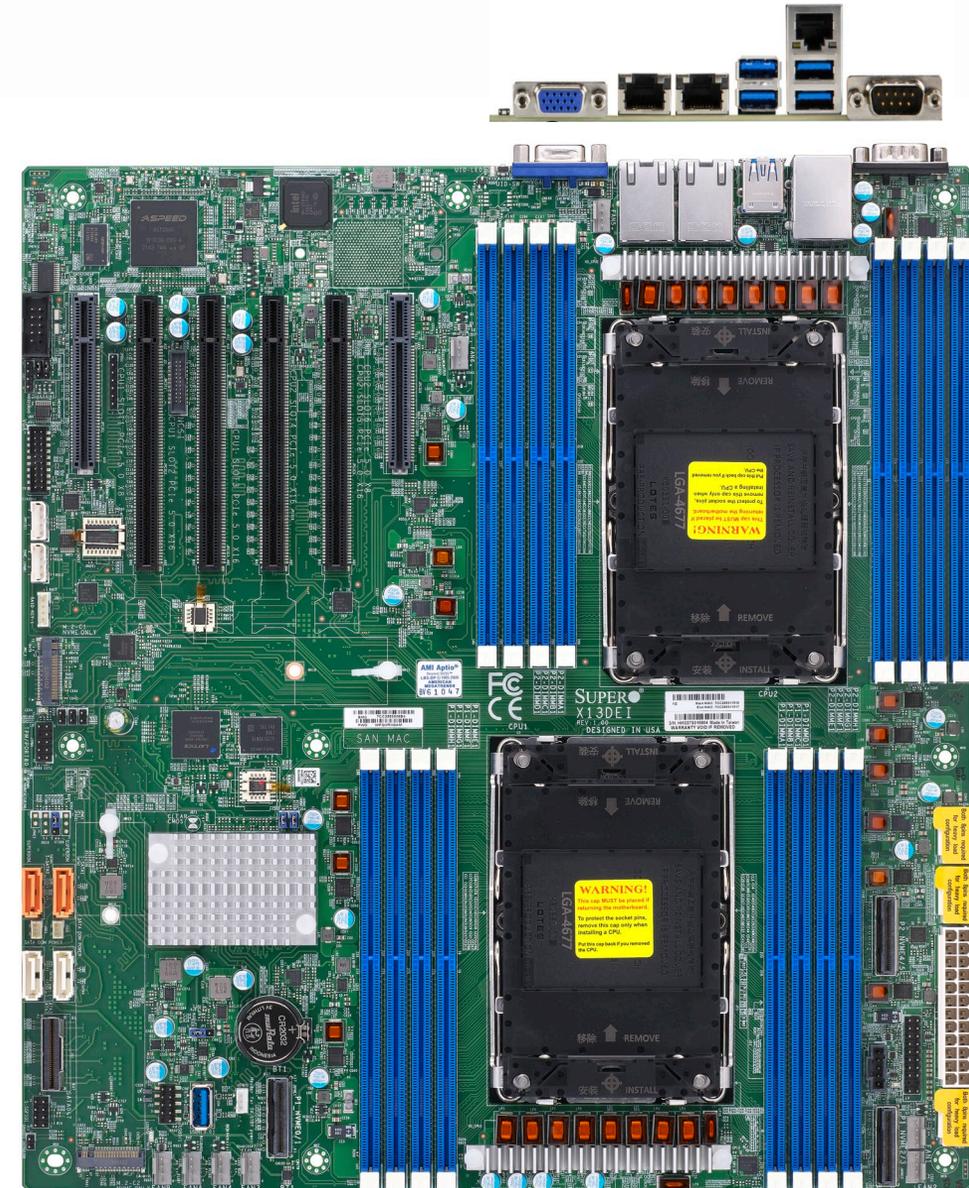


Key Features:

- Dual CPU Socket-E up to 350W TDP(Non HBM)
- 4 UPIs designed for up to 16 GT/s
- 16 DIMMs ECC DDR5 for up to 4800MTS (1DPC)
- 4 PCI-E 5.0 x16 slots
- 2 PCI-E 5.0 x8 slots
- 2 PCI-E 4.0 NVMe x2 M.2 22110/2280*
- 6 PCI-E 5.0 NVMe x4 ports via 3x MCIO x8 connectors
- 6 USB 3.2 Gen1 (4 rear + 2 Header)
- 3 USB2.0 (2 Header+ 1 Type A)
- 10 SATA3 ports(8 from Slim SAS x8+2 SATADOM)
- 2 LAN ports 1Gb(-B:BCM5720) / 10Gb(-BT:BCM57416)
- BMC AST2600 with dedicated LAN and VGA
- Add one I2C connector for BPN CPLD OOB update
- Rear UID button with BMC reset function.
- Compatible SYS-221P/621P/741P mainstream servers.

Market segment:

- Channel / SI/VAR/OEM



Dimension:
12.1" x 13.1"

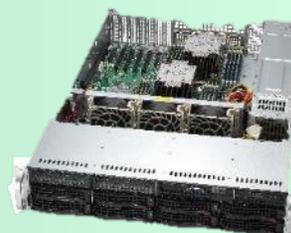
X13DEI-(T)- Mainstream



- E-ATX form factor
- Standard I/O Expansions
- Serves as a great entry-level building block solution



SYS-741P-TRT
4U Workstation Server
Support up to 10 drivers



SYS-621P-TRT
2U Rackmount Server
Support up to 10 drivers



SYS-221P-C9RT
2U Rackmount Server
Support up to 18 drivers



SSG-621E-ACR12H/L
2U Rackmount Server
Support up to 14 drivers



SSG-621E-ACR16H/L
2U Rackmount Server
Support up to 18 drivers



SSG-631E-E1CR16H/L
3U Rackmount Server
Support up to 18 drivers



SSG-641E-E1CR24H/L
4U Rackmount Server
Support up to 26 drivers



SSG-641E-E1CR36H/L
4U Rackmount Server
Support up to 38 drivers

Mainstream
Server

Storage
Server

X13DAI-T Motherboard Details

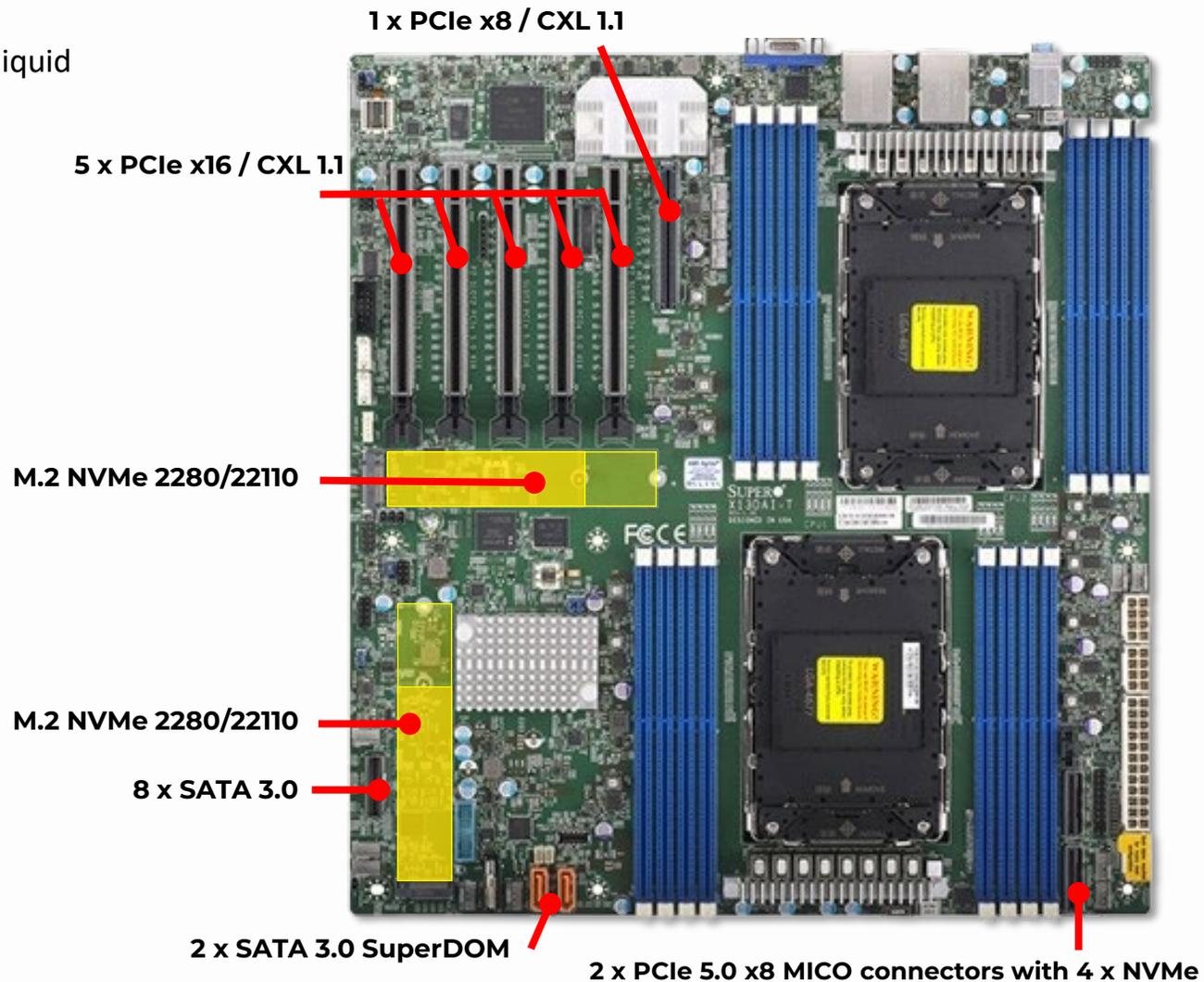


Key Features:

- Dual Sapphire Rapids CPU(XCC/MCC) Socket E up to 350W TDP (liquid cooling needed), 4 UPI up to 16 GT/s
- Intel Chipset C741
- 16 x DIMM, 1DPC ECC DDR5 designed for up to 4800 MT/s
- 10 x SATA3 (8 SATA with RAID 0/1/5/10 + 2 SuperDOM) ports
- 4 x PCIe 5.0 x4 NVMe ports via 2 SlimSAS x8 (RAID 0/1/5/10)
- 2 x PCIe 5.0 NVMe M.2 (2280/22110)
- BMC AST 2600 (with shared LAN)
- Dual Broadcom BCM 57416 10G LAN
- 5 x PCIe 5.0 x16/CXL 1.1, 1 x PCIe 5.0 x8/CXL1.1
- 6 x USB 3.0 5Gbs (4 Type A rear, 2 via header),
- 1 x USB3.2 Gen2 10Gbs (1 Type C front)
- 1 x TPM 2.0 header
- 1 x COM header, 1x VGA port
- Onboard HD7.1 Audio
- Dimension: 12" x 13" (E-ATX Form Factor)

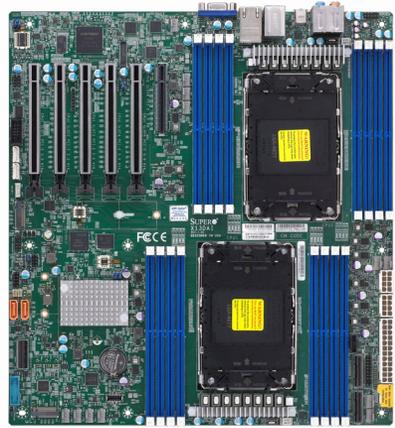
Market segment:

Workstation Applications – Media & Entertainment,
Engineering Design, Scientific Modeling, AI / Channel / SI/VAR/OEM

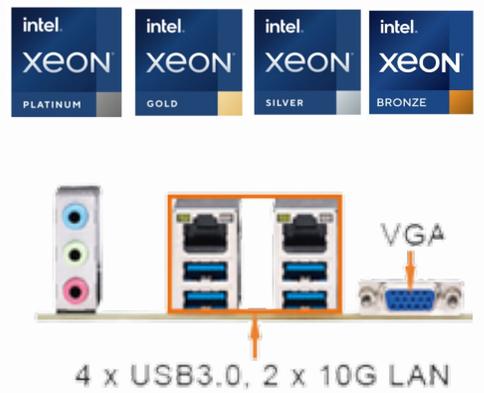


High Performance Workstation

- E-ATX form factor
- Optimized Building Block Chassis
- Standard I/O Expansion
- ISV certified



X13DAI-T



Workstation Server



+

Nvidia RTX 6000 Ada



Nvidia RTX A6000, RTX A2000



Nvidia Quadro RTX T1000, RTX T400



Focus on the workloads

- AI/ML inference such as Generative design for Manufacturing, AEC, Media & Entertainment
- Virtual GPU and VDI solution such for Engineering & Sciences
- Professional Video processing with MPEG-2, VC-1, H.264, H.265, VP8, VP9, and AV1

Focus on the workloads

- Real-time visualization rendering for 3D design or simulation
- Virtual GPU and VDI solution (RTX A6000 support)

Focus on the workloads for Entry-Level Users

- Visualization rendering for 2D/3D design, simulation or video editing

X13DEG-QT Motherboard Details



Key Features:

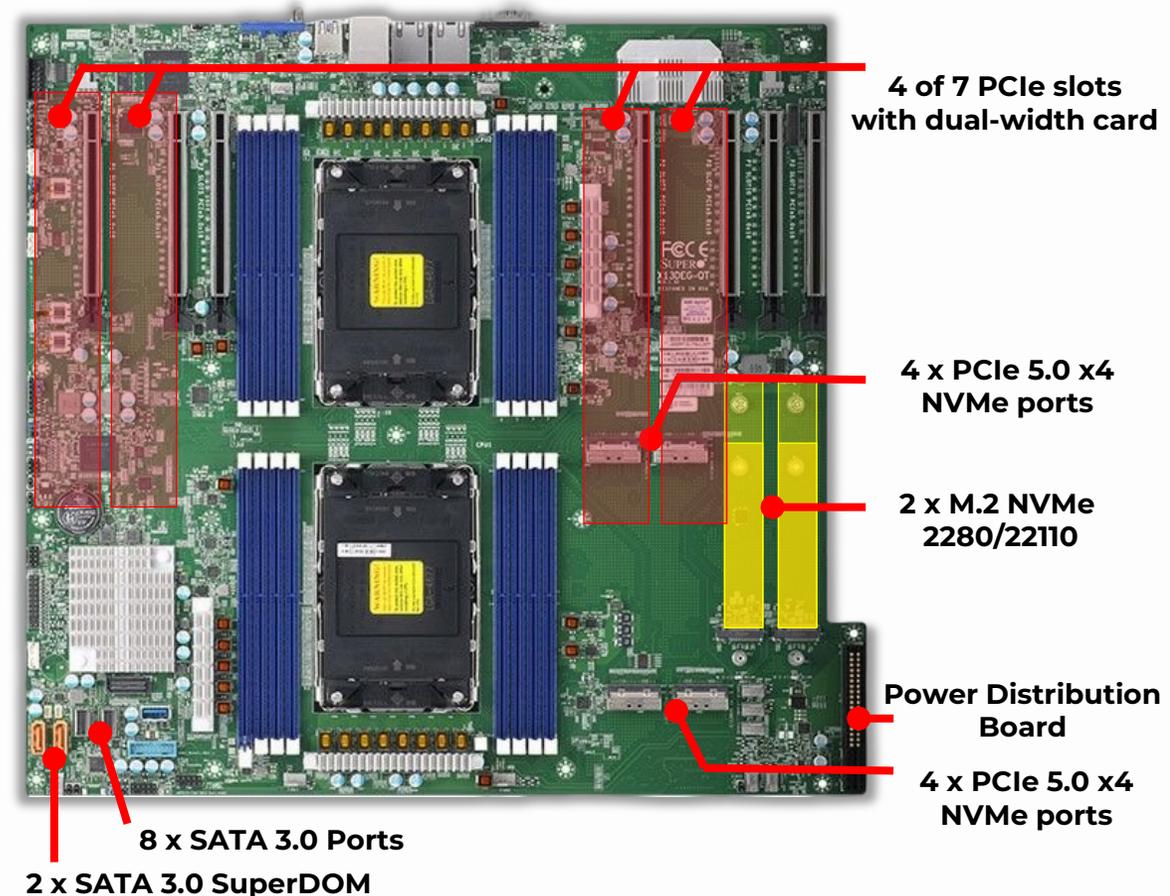
- Intel® Dual 4th Xeon® CPU(XCC/MCC) and Intel® Xeon® CPU MAX Series, Socket E, Up to 350W TDP (Liquid cooling required), 4 UPI up to 16 GT/s
- Intel Chipset C741
- 16 x DIMM, 1DPC ECC DDR5 designed for up to 4800 MT/s
- 10 x SATA3 with RAID 0/1/5/10 (8 SATA ports via 2 SlimSAS x4 + 2 SuperDOM)
- 8 x PCIe 5.0 x4 NVMe ports via 4 MCIO x8 (RAID 0/1/5/10)
- 2 x PCIe 5.0 NVMe M.2 slots (2280/22110)
- BMC AST 2600 with RoT2.0, dedicated LAN port
- Dual Intel X550-AT2 10GbaseT LAN ports
- 7 PCIe 5.0 x16/CXL 1.1
- 7 USB3.2 Gen1 5Gb/s (3 Type A & 1 Type C rear, 1 Type A internal, 2 via header)
- 1 x TPM 2.0 header
- 2 x COM (1 COM port rear, 1 header)
- 1x VGA port
- Onboard HD7.1 Channel Audio header
- Dimension: 14.56" x 15.28" (370 mm x 403 mm)

System SKUs:

- SYS-741GE-TNRT (4U/Rack)

Market Segment:

- GPU Workstation Applications –HPC, DL Training & Data Analytics, DL Inference, VDI, 3D Visualization.



Win10, Win11, Win Server



RHEL, CentOS, Oracle, Rocky, SLES, Ubuntu



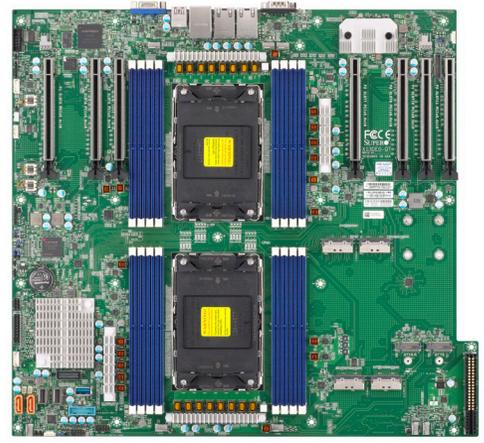
VMWare ESXi 8.0

GPU MAX Workstation



AI Workloads:

<p>Large Language Model GPT-3 175B</p>	<p>Object Detection, Light-Weight RetinaNet</p>	<p>Medical Imaging 3D U-Net</p>	<p>Natural Language Processing BERT</p>
<p>Object Detection, Heavy-Weight Mask R-CNN</p>	<p>Speech Recognition RNN-T</p>	<p>Image Classification ResNet-50 v1.5</p>	<p>Recommendation DLRM-DCnv2</p>



X13DEG-QT

USB 3.2 Gen1 (Type A + Type C)
2 x USB 3.2 Gen1 + BMC LAN

10Gbaset LAN

COM

VGA

Workstation Server



Liquid Cooling

SYS-751GE-TNRT

- Verified GPU PCIe Cards:**
- 4x H100 w/ Liquid Cooler
 - 4x A100 w/ Liquid Cooler



Air Cooling

SYS-741GE-TNRT

- Verified GPU PCIe Cards:**
- 2x H100 NVL or 4x H100 or 4x A100
 - 4x RTX 6000 Ada or 4x RTX A5500
 - 4x L40 or 7x L4
 - AMD MI210
 - Intel Data Center GPU

GPU Platforms



Highest Performance and Flexibility for AI/ML and HPC Applications

HGX Platforms



8U-8GPU SYS-821GE-TNHR

Integrated Performance, HGX H100 8-GPU



5U/4U-4GPU SYS-421GU-TNXR

Scalable Performance, HGX H100 4-GPU

PCIe Gen5 Platforms



5U/4U-10GPU SYS-421GE-TNRT

Dual/Single Root, Direct Connect PCIe GPU



4U-4GPU SYS-741GE-TNRT

Flexible Solution, PCIe GPU

BigTwin®

Industry-leading Multi-node Architecture

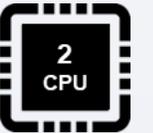


Highly configurable 2U 4-node and 2U 2-node systems optimized for density or storage

- Optimized thermal design with liquid cooling options
- All-hybrid hot-swappable NVMe/SAS/SATA drive bays – Up to 12 drives per node
- Resource Saving Architecture with shared power and cooling for increased efficiency
- Flexible networking with up to 400G Ethernet per node

Key Applications

Enterprise Server • Cloud Computing • Big Data Analytics • High Performance Computing • Hyperconverged Storage • AI Inference and Machine Learning



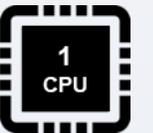
GrandTwin™

Multi-Node Architecture Optimized for Single-Processor Performance



Resource Saving Architecture with Modular Design

- Front and rear I/O configurations available
- Integrated GrandTwin module per node with on-board networking and management interfaces
- Up to six 2.5" NVMe, SAS or SATA drives per node
- Flexible networking options with OCP 3.0 NIC compliant AIOM slots

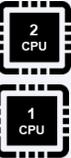


Key Applications

Enterprise Server • Cloud Computing • Big Data Analytics • High Performance Computing • Content Delivery Network • Electronic Design Automation

CloudDC

All-in-one Rackmount Platform for Cloud Data Centers



Flexible 1U and 2U Rackmount Systems for Multi-Workload Environments

- Great for mid-to-large size compute applications.
- U.2 NVMe SSD support with up to 12 drives in 2U (Optional SAS and SATA configurations)
- Up to 2 PCIe slots in 1U or 6 PCI-E slots in 2U
- Up to 2 AIOM slots for flexible networking options

Key Applications

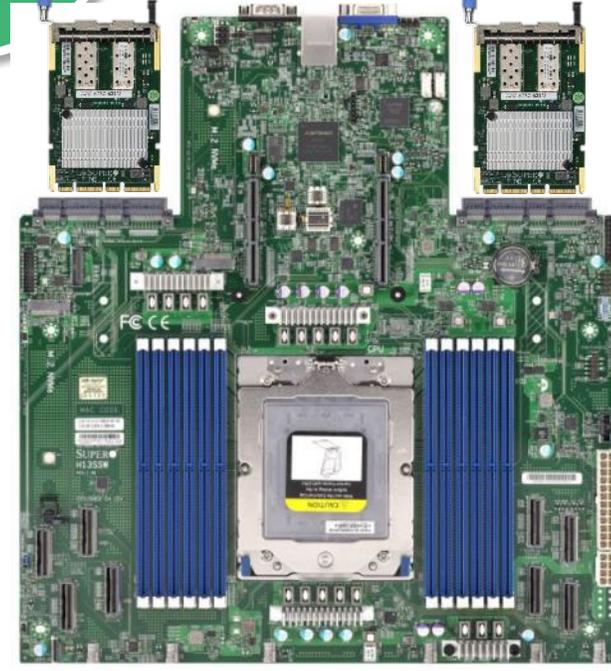
Cloud Computing • Web Servers • Virtualization • File Servers • Head-Node Server • Hyperconverged Storage

Gen13 CloudDC



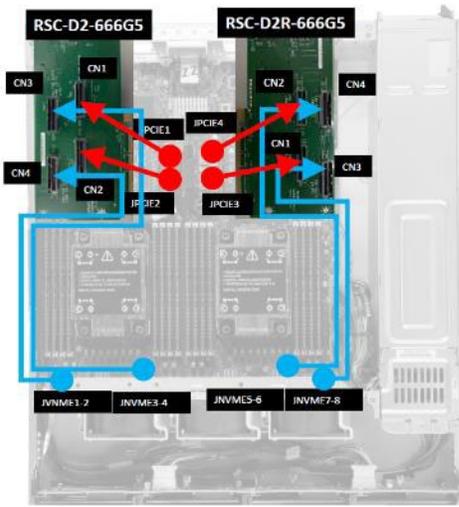
- Cloud optimized with load balancing
- The highest cost optimized with great flexibility in I/O and storage configurable solution
- High Volume Optimized for Data Center
- TCO

Symmetric
Layout for
Balanced
Load

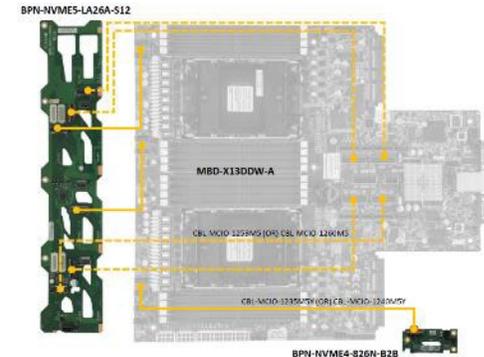
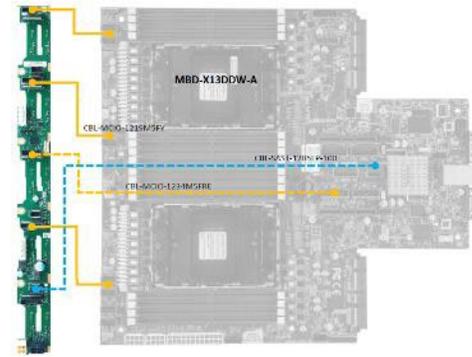


Gen13 CloudDC

- SYS-611C-TN4R
- SYS-121C-TN2R
- SYS-121C-TN10R
- SYS-621C-TN12R
- AS -1015CS-TNR
- AS -1115CS-TNR
- AS -2015CS-TNR



SYS-621C-TN12R
10 U.2 NVMe
Default 12 SATA
Optional 12 NVMe via Cable Kits
Optional 2 rear HDD Kit



SYS-121C-TN2R
8 2.5" SATA
Optional Optical Drive Kit



SYS-611C-TN4R
4 3.5" SATA
Optional HDD /
Optical Drive Kits



SYS-121C-TN10R
10 U.2 NVMe/SATA



Hyper

Best-in-class Performance and Flexibility Rackmount Server



High Performance 1U and 2U Rackmount Systems

- Free-air and liquid cooling options for maximum performance and efficiency
- Highest memory capacity available in the Rackmount product family
- U.2 NVMe SSD support with up to 24 drives in 2U (Optional SAS and SATA configurations)
- Up to 3 PCIe slots in 1U or 8 PCI-E slots in 2U
- Tool-less system for simplified maintenance



Key Applications

Enterprise Server • Cloud Computing • Big Data Analytics • High Performance Computing • Hyperconverged Storage • AI Inference and Machine Learning

One MB designed for multiple system solutions



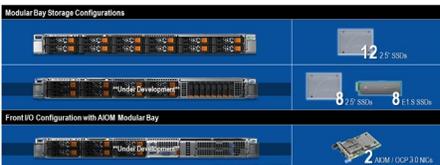
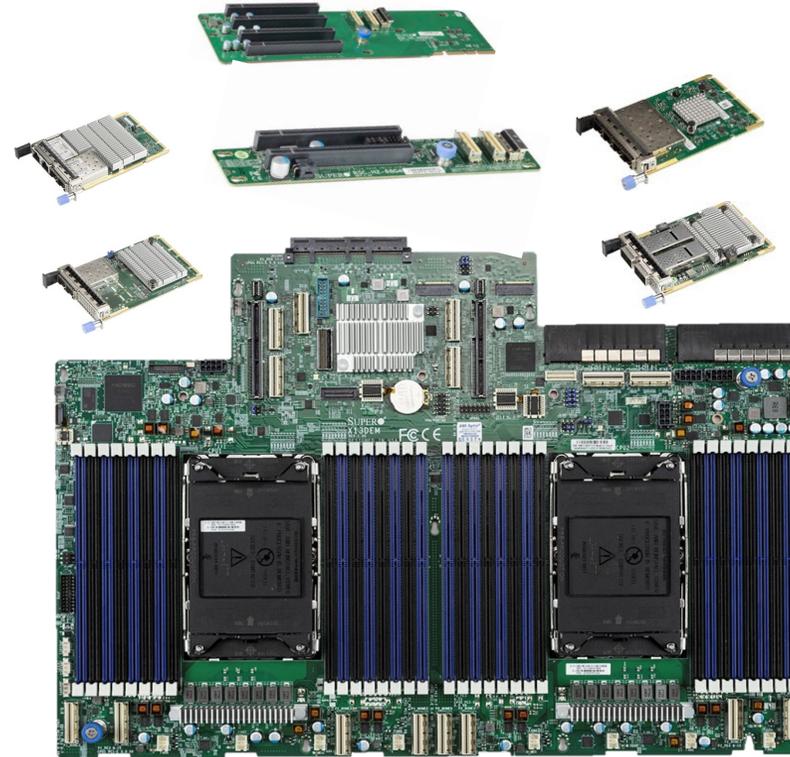
- The most advance architecture in motherboard and system design to give the highest optimization and flexibility with new technologies innovation

X13 Hyper

- SYS-121H-TNR
- SYS-221H-TNR
- SYS-621H-TN12R
- SYS-221H-TN24R
- SYS-221HE-FTNR
- SYS-221HE-FTNRD

- Total 7 Riser card
 - RSC-H-66G5L
 - RSC-H-6G5L
 - RSC-H26888G5L
 - RSC-H-68G5
 - RSC-H2-6888G5S
 - RSC-H2-668G5S
 - RSC-H2-68G5

- Total 6 Backplane
 - BPN-NVME5-HS119N-S8L
 - BPN-NVME5-HS119N-S4R
 - BPN-NVME5-LA26A-S12
 - BPN-NVME5-HS219N-S8
 - BPN-NVME5-HS219N-S24
 - BPN-NVME5-HE211N-S6



AS -2025HS-TNR



SYS-221HE Series
Short Depth, Front IO



SYS-121H-TNR



SYS-221H-TNR
8/16 U.2 NVMe or
8/16/24 2.5" SATA

SYS-221H-TN24R
24 U.2 NVMe

X13 SuperBlade[®]

Ultra High-Density Multi-Node Systems for Enterprise, Cloud, HPC, and AI Applications



Optimized for Performance, Density and Advanced Networking

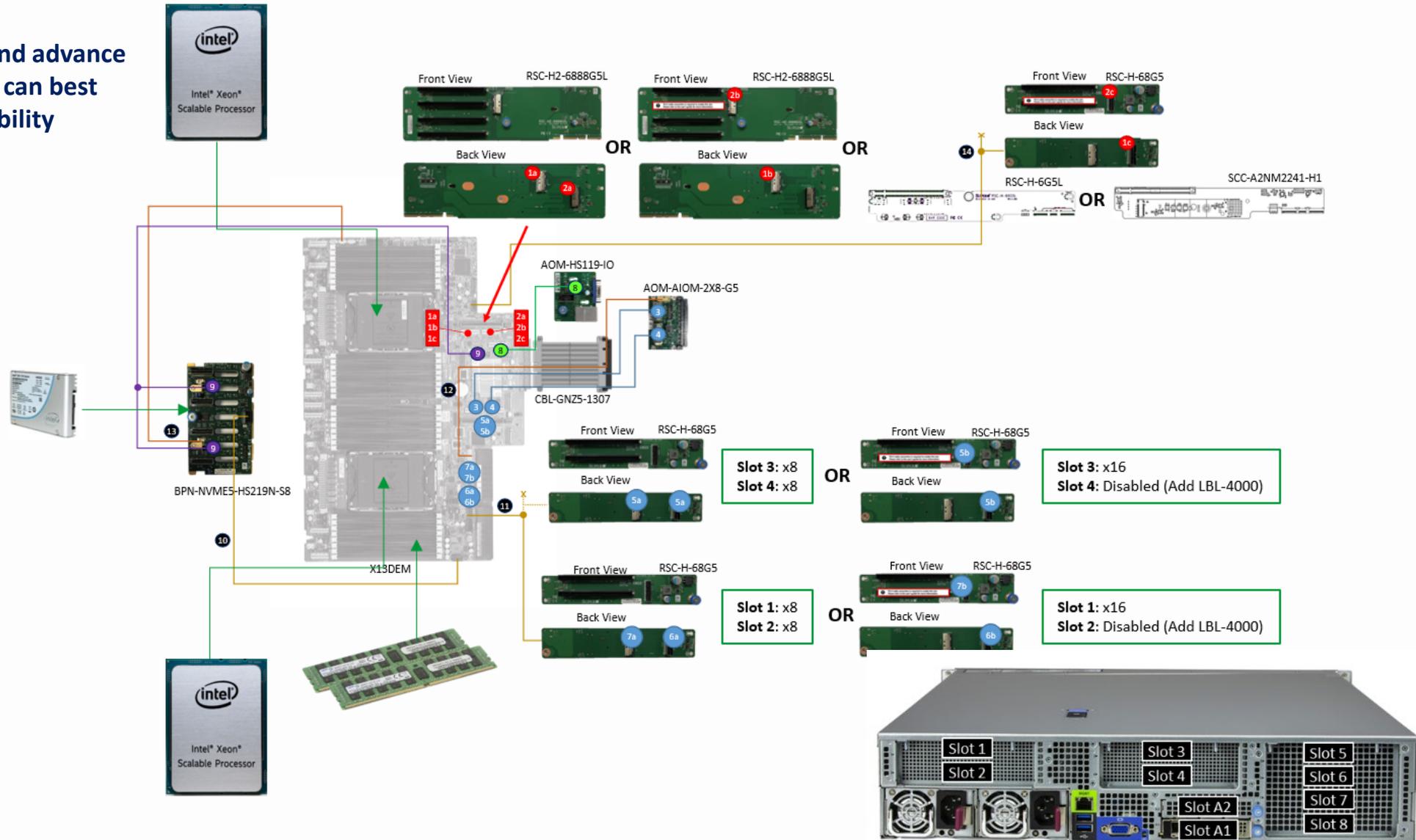
- Up to 20 nodes in 8U or 10 nodes in 6U with integrated switches
- Single or dual 4th Gen Intel[®] Xeon[®] Scalable processors with air-cooled support for up to 350W TDP CPUs
- Up to 32 DIMM slots per node supporting DDR5-4800
- High-performance networking with up to 400G InfiniBand and Ethernet support
- Up to 4 GPU or network cards per node
- High-performance NVMe drives in E1.S, U.2 and M.2 form factors
- Direct liquid cooling option

Key Applications

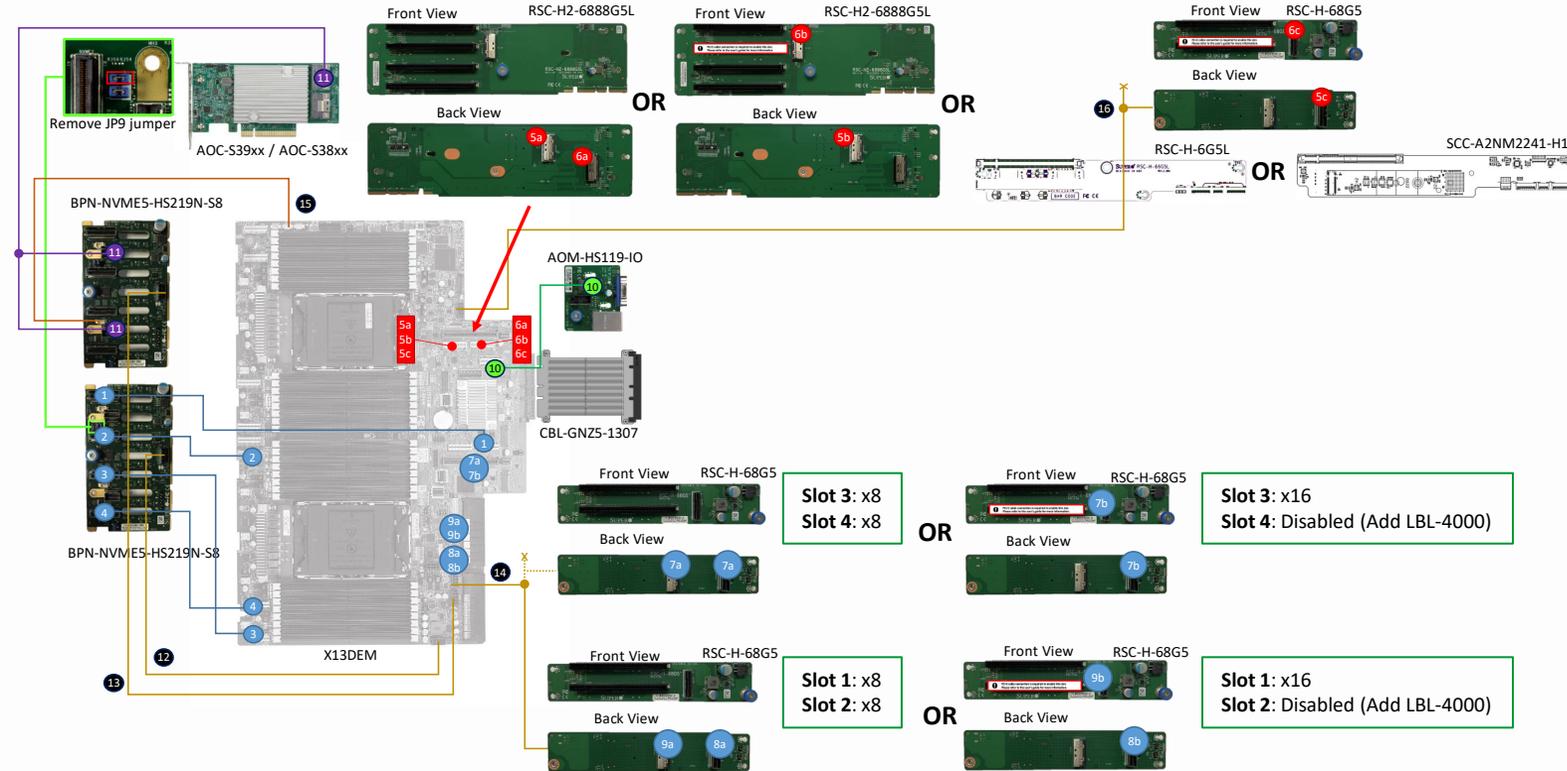
- AI
- HPC
- Cloud
- EDA
- CDN
- Virtualization
- Financial Services

Complexity with advance system architecture

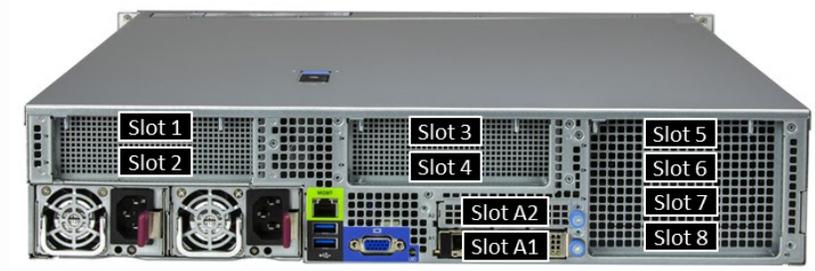
- **Why L10:** With this complexity and advance system architecture, Supermicro can best handle and provide highest reliability
- Higher Quality
- Thermal
- Gen5 I/O validation
 1. Cable
 2. RSC



Optimized cables routing



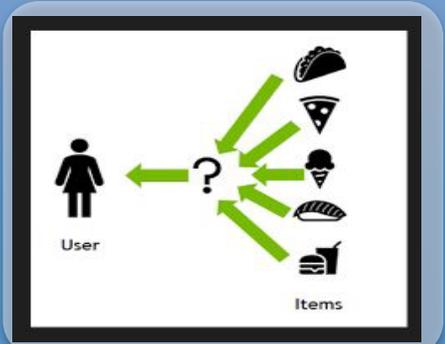
#	Description	SMC Part Number	MFG	MFG Part Number	#	Description	SMC Part Number	MFG	MFG Part Number
1	NVME	CBL-MCIO-1250M5L	AMP	RMC74-4882-1	7a	PCI-E	CBL-GN24-1227M5YR21	LUX	LUDG2020-SD-R
2	NVME	CBL-MCIO-1219M5L	MOL	2157321061	7b	PCI-E	CBL-GN24-1227M5YRR16	LUX	LUDG2019-SD-R
3	NVME	CBL-MCIO-1234AM5LFRE	MOL	2157321062	8a	PCI-E	CBL-MCIO-1233M5R	LUX	LUDMM035-SD-R
4	NVME	CBL-MCIO-1234M5L	MOL	2157321063	8b	PCI-E	CBL-MCIO-1233M5R	LUX	LUDMM035-SD-R
5a	PCI-E	CBL-MCIO-1222AM5	LUX	LUDMM071-SD-R	9a	PCI-E	CBL-MCIO-1232M5	LUX	LUDMM036-SD-R
5b	PCI-E	CBL-MCIO-1222AM5	LUX	LUDMM071-SD-R	9b	PCI-E	CBL-MCIO-1233M5R	LUX	LUDMM035-SD-R
5c	PCI-E	CBL-MCIO-1226AM5R	LUX	LUDMM069-SD-R	10	IO	CBL-SAST-1225LP	MOL	2113013134
6a	PCI-E	CBL-MCIO-1222AM5	LUX	LUDMM071-SD-R	11	SAS	CBL-SAST-1276F-100	3M	8Y8-253A-S46
6b	PCI-E	CBL-MCIO-1226AM5	LUX	LUDMM070-SD-R	12	POWER	CBL-PWEX-1142-60	FXC	WDH0806-ZZ015-DF
6c	PCI-E	CBL-MCIO-1226AM5R	LUX	LUDMM069-SD-R	13	POWER	CBL-PWEX-1142B-70	BLW	76396-500W



#	Description	SMC Part Number	MFG	MFG Part Number
14	POWER	CBL-PWEX-1136YB-25	BLW	76455-600W
15	I2C (BMC)	CBL-CDAT-1062	MOL	686030496
16	POWER	CBL-PWEX-1136YB-25	BLW	76455-600W



Digital Twin



Recommendation System

Digital Twin

Reach **\$125.7B** by 2030, growing at a CAGR of **39.48%** from 2022 to 2030

From manufacturing to healthcare, facilities management to product design, digital twins offer the technology behind improved operations, innovative and product testing

1. Cut costs (79%)
2. Advance technology in their organizations (77%)
3. Reduce time to market for new products and services (73%)
4. Introduce new business models (67%)
5. Increase customer-centricity (65%)

Application	Revenue Share, 2021 (%)
Agriculture	2.7%
Manufacturing	16.5%
Telecommunication	5.5%
Aerospace & Defense	17.9%
Retail & Consumer Goods	6.5%
Residential & Commercial	8.3%
Healthcare & Lifesciences	8.8%
Energy & Utilities	11.5%
Automotive & Transport	19.8%
Others Industries	2.5%



Potential Customers



Digital Twin Industry Landscape

Solution Provider	Manufacturing AKSELOS, Ansys, XMPRO, BOEING, AVEVA, GE Digital, Rockwell Automation, ptc, arvizio, SIEMENS, aras	AEC Industry Bentley, sensat, DASSAULT SYSTEMES, arvizio Building Management: COGNITIVE, ARCHIBUS, cityzenith, cohesion, Sense facilities, NEURON, Buddy, vidya, i Lens Asset Management: AKSELOS, AVEVA, GISGRO, Bentley, ORACLE, COGNITE	Urban Design AccuCities, imerso, cityzenith, 51 WORLD, URBANETIC, GeoSpock, CESIUM, Bentley, DASSAULT SYSTEMES, CSIRO, nextspace, FORUM 8	Consulting NTT DATA, SoftBank, HITACHI, OPTIM, CTC, FUJITSU, Deloitte, Pacific Consultants				
	Digitalization	Surveying Drone: DJI, DENSO, GNSS: TOPCON, Leica, Laser scanner: TOPCON, Nikon, Leica, FARO, RIEGL ArchiTwin, TerraDrone, Satellite: NTT DATA, Synspecive, LIXIA, SPACE SHIFT	MAP CESIUM.JS, esri, ZENRIN, 国土地理院, HITACHI Inspire the Next	IoT NTT DATA, Panasonic, CYBERNET, SII, SONY	3DCAD AUTODESK, SketchUp, FUKUI COMPUTER, GRAPHISOFT, ENO DESIGN SYSTEM, Bentley	Point Cloud AUTODESK, ELYSIUM, SCANX, ArchiTwin, Twinsity	Visualize SYMMETRY DIMENSIONS INC, arvizio	3D Engine unity, UNREAL, NVIDIA

Solutions:

- 1) GPU WS Tower/4U/5U GPU Server
- 2) Hyper Server
- 3) SuperBlade Server
- 4) 4U 60/90-bay storage server

<https://www.alliedmarketresearch.com/digital-twin-market-A17185>

<https://www.techrepublic.com/article/digital-twins-are-moving-into-the-mainstream/>

Recommendation System

Reach **\$54B** by 2030, growing at a CAGR of **37%** from 2022 to 2030

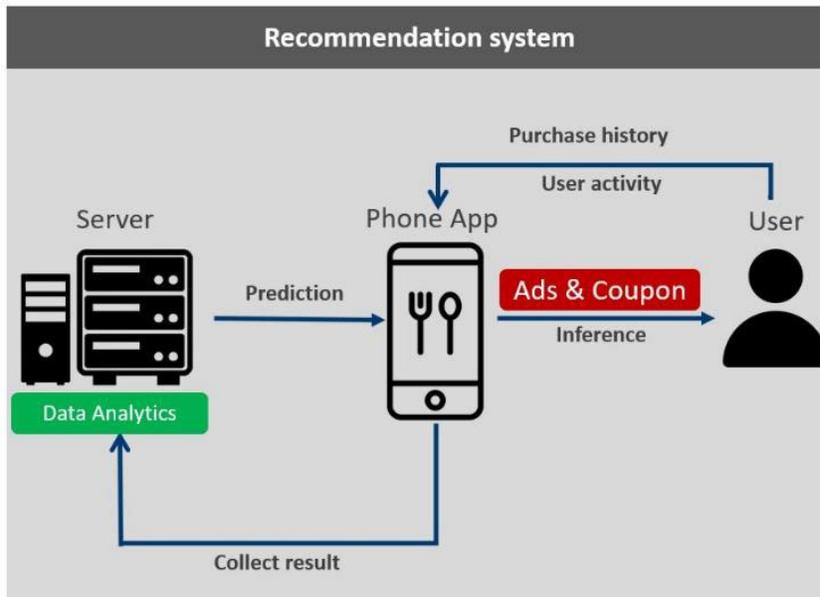
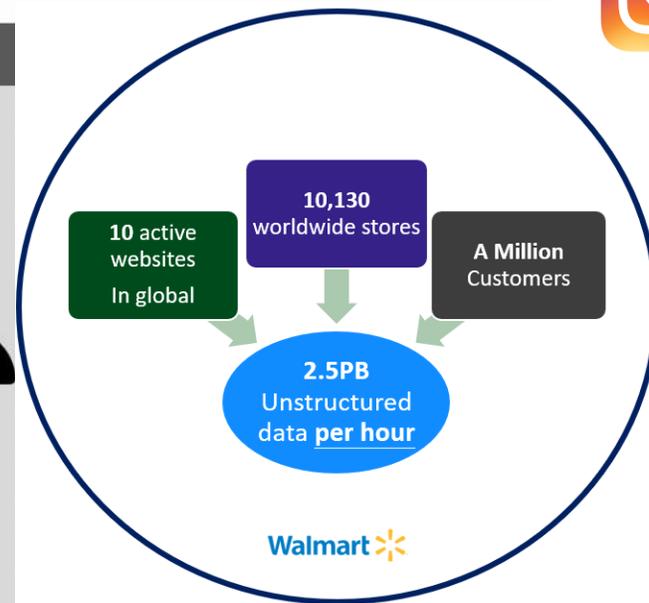
E-commerce, multimedia content platforms, and social networks that need real time processing power

Potential Customers



Solutions:

- 1) 4U/5U GPU Server/Delta Next
- 2) Hyper-E Server
- 3) CloudDC Server
- 4) All flash storage server



<https://insidebigdata.com/2022/06/05/bad-data-costs-u-s-companies-trillions-how-data-quality-audits-can-help/#:~:text=Bad%20data%20costs%20U.S.%20companies%20an%20estimated%20243.1%20trillion%20per,lost%20productivity%2C%20ineffective%20marketing%20campaigns.>

[https://stratresearch.com/report/recommendation-engines-market#:~:text=Market%20Overview,period%20\(2022%E2%80%932030\).](https://stratresearch.com/report/recommendation-engines-market#:~:text=Market%20Overview,period%20(2022%E2%80%932030).)

How to Hit Growth Target?

- 1.) Strong product solutions including GPU, Twin, Hyper, CouldDC, Ultra, WIO, Storage, SuperBlade, and Mainstream platforms with Supermicro product innovation design.
- 2.) Best product design quality with strong engineering support.
- 3.) Design in both USA and Taiwan for better business support in different regions.
- 4.) Time to Market with strong global operation support.
- 5.) Global services and TS support in US, Asia, and Europe.
- 6.) We have dedicated PMs, FAEs, and BDs available to support our sales and engage with customers to grow our business and market share.

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